Essemtec to Showcase Advanced Dispensing, Jetting and Hybrid Packaging Solutions at NEPCON Shanghai 2026

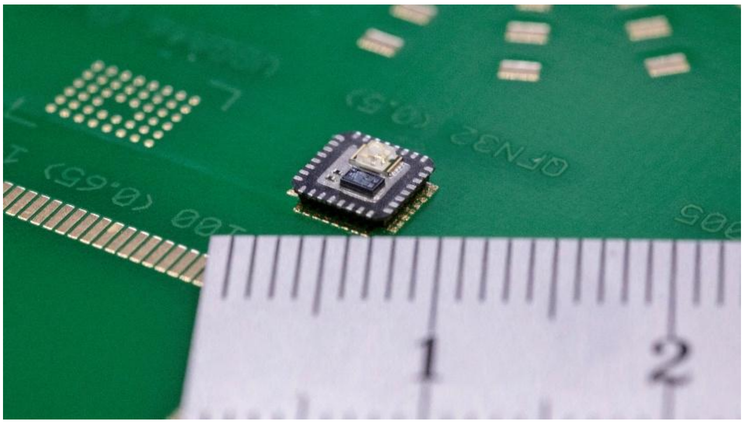
Essemtec, a global leader in adaptive SMT manufacturing solutions, will participate at NEPCON Shanghai 2026, taking place from June 2–4, 2026, in Shanghai, China. Visitors are invited to discover Essemtec's latest innovations together with its Chinese partner Intellengine at Booth 1H70.

During the exhibition, Essemtec will present live demonstrations of its FOX Ultra All-in-One and PUMA Ultra All-in-One platforms, highlighting the company's expertise in advanced dispensing, high-speed jetting and hybrid packaging applications.

As electronic devices continue to become smaller, more powerful and increasingly complex, manufacturers are facing growing demands for precision, flexibility and process integration. Essemtec's solutions are specifically designed to address these challenges, supporting applications such as Chip-on-Chip, System-in-Package (SiP), Package-on-Package (PoP), advanced component stacking and other hybrid assembly processes.

Particular focus will be placed on Essemtec's advanced jetting and dispensing technologies for fine-pitch and advanced packaging applications, including 008004 pad sizes and pitches as fine as 0.3 mm. The live demonstrations will highlight high-speed solder paste jetting capabilities reaching up to 1.1 million dots per hour, as well as precise dispensing of epoxy and silver epoxy materials.

Essemtec's solutions support a wide range of advanced processes including underfill, meter-mix dispensing, micro coating, cavity dispensing and dispensing at different Z-levels for complex substrates and advanced assemblies. The company's platforms are also designed to support leadframes and carriers, enabling high-precision manufacturing for hybrid packaging and next-generation electronic applications.



By combining high-accuracy placement, advanced dispensing technologies and Jet-on-the-Fly capabilities within flexible All-in-One platforms, Essemtec enables manufacturers to optimize floor space, reduce handling and increase process efficiency for prototyping, NPI and high-mix production environments.

“Hybrid packaging and advanced dispensing applications require an exceptional level of flexibility, accuracy and process control,” said Jacky Zhou (周杰), Country Sales Manager China. “At NEPCON Shanghai, we are excited to demonstrate how Essemtec’s All-in-One solutions help manufacturers address these new production challenges while maintaining efficiency, scalability and process versatility.”

Visitors to Booth 1H70 will have the opportunity to discuss their manufacturing challenges with Essemtec and Intellengine specialists and discover solutions for advanced SMT assembly, dispensing, jetting and hybrid packaging applications.

For more information about Essemtec’s solutions, visit Essemtec and Intellengine.